

ELECTROPLATING PROCESS CHAMBER
WITH PRE-WETTING AND RINSING CAPABILITY

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10 ABSTRACT OF THE DISCLOSURE

15 A plating cell has an inner plating bath container
for performing electroplating on a work piece (e.g., a
wafer) submerged in a solution contained by the inner
plating bath container. A reclaim inlet funnels any
solution overflowing the inner plating bath container
back into a reservoir container to be circulated back
into the inner plating bath container. A waste channel
is also provided having an inlet at a different height
20 than the inlet of the reclaim channel. After
electroplating, the wafer is lifted to a position and
spun. While spinning, the wafer is thoroughly rinse
with, for example, ultra pure water. The spin rate and
height of the wafer determine whether the water and
25 solution are reclaimed through the reclaim channel or
disposed through the waste channel.